



Low Power Design - Jointly towards 28FD-SOI

JOACHIM RODRIGUES, LUND UNIVERSITY



Overview

All PhD projects will be presented at the poster session tomorrow

- 65 nm
 - Custom Full-adder for 300 mV- Cristoph Müller
 - Energy efficient decoders- Reza Meraji
 - ULV DC-DC Converter – Babak Mohamadi
 - Digital baseband for a wake-up receiver- Nafiseh Mazloum
 - Master Thesis projects
- 28 FD-SOI
 - 16 kB low power memory– Babak Mohamadi
 - Synthesizable latch based memory- Oskar Andersson





300mV Full-adder with fast Carry propagation

CHRISTOPH MÜLLER



Custom Full Adder Cell for Sub- V_t

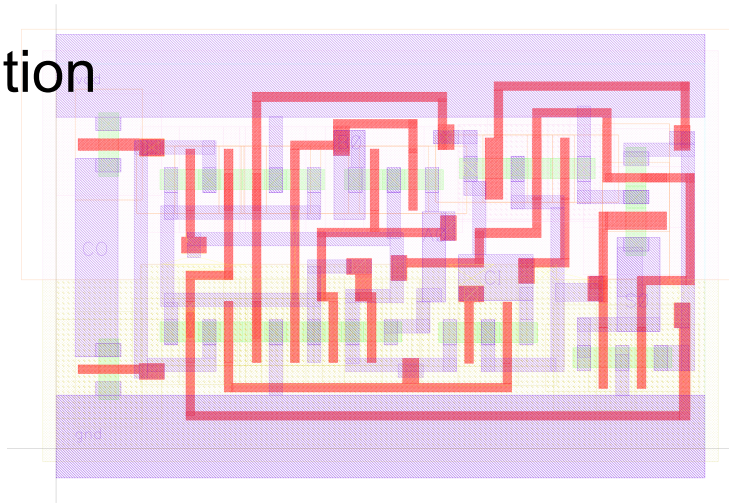
Goal: FA for Ripple Carry Adder at 300 mV

- Simplest Adder design, no carry propagation circuitry leaking
- Throughput limited by carry propagation

→ Optimized for a fast C_i to C_o path

Survey over 36 Architectures

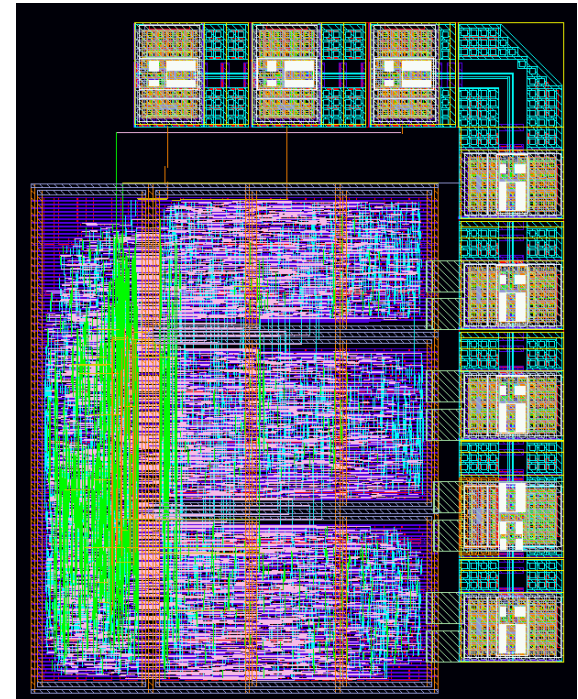
- Optimization, characterization and seamless PDK integration of winning design
- 23 T, Mixed Pass-Transistor/CMOS implementation, dual- V_t balancing



Test Designs

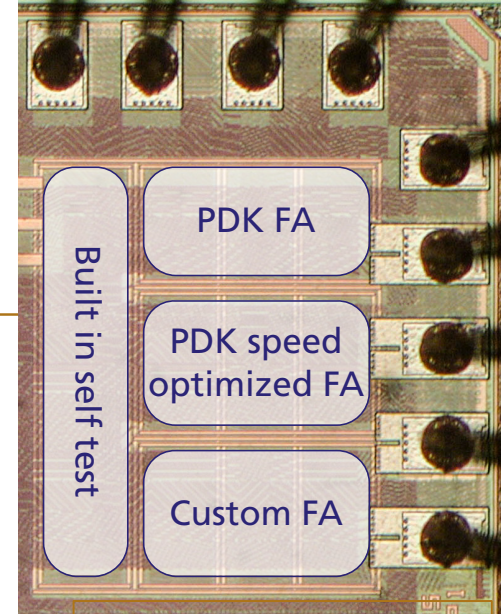
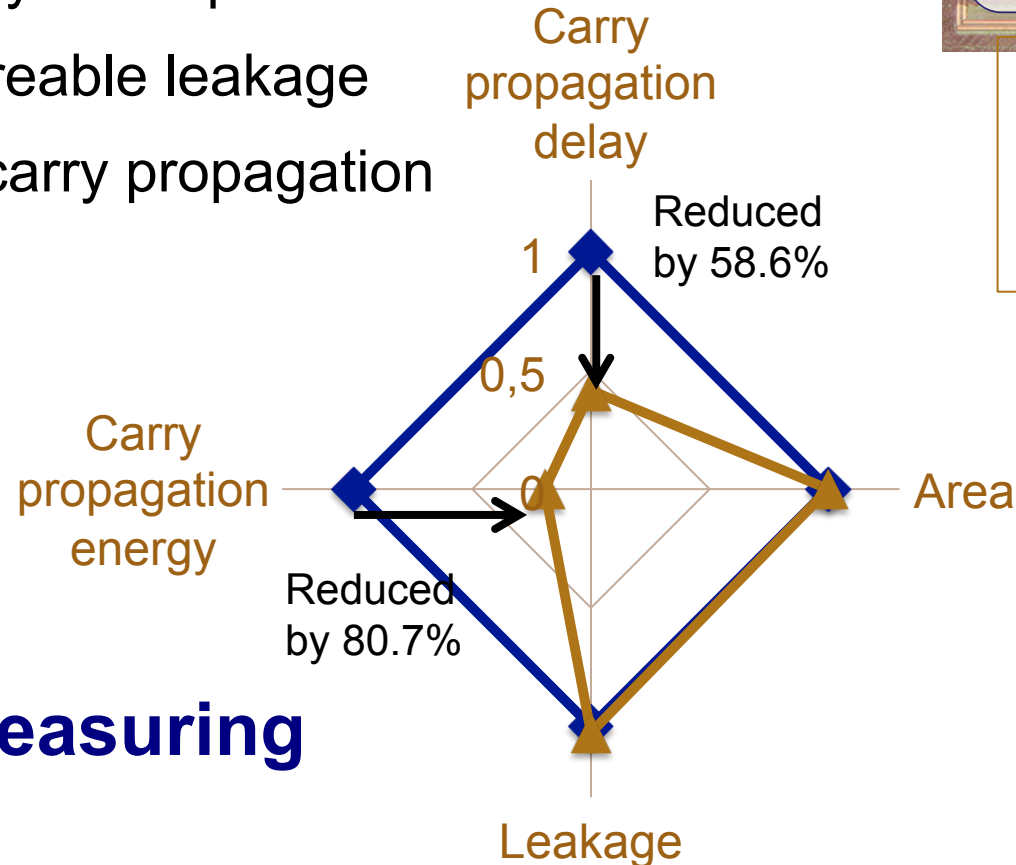
Testbed

- Three 24x24 ripple carry array multipliers, realized by
 - custom FAs
 - PDK FAs (different constraints)
- Separate power domains for measurement
- BIST to reduce pad count



Expected Results

- Simulation results in comparison to FA from PDK:
 - Lower dynamic power
 - Compareable leakage
 - Faster carry propagation



- ◆ PDK speed optimized
- ▲ Custom FA

Status: Measuring



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Energy Efficient Decoders for an Ultra Low Power Radio

REZA MERAJI

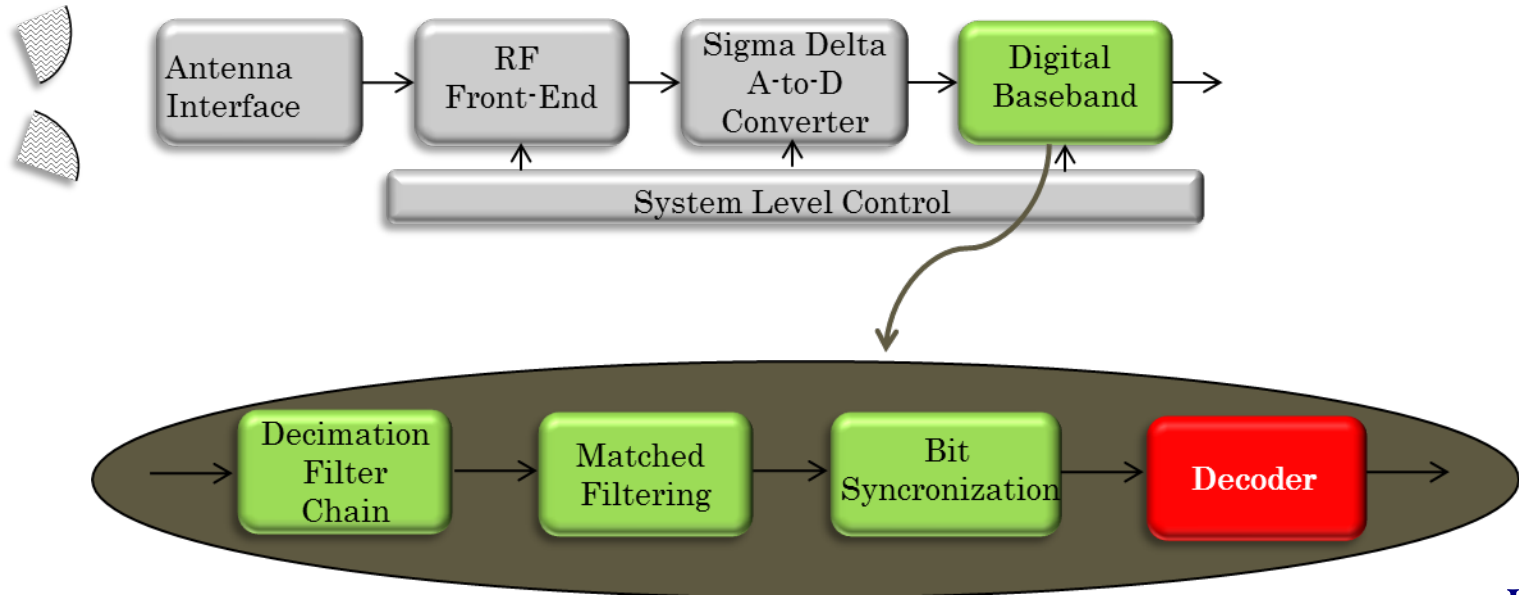
Graduation is planned for October 17th



An Ultra Low Power Receiver Chain

Project Goal: A complete low power receiver chain from antenna to decoder

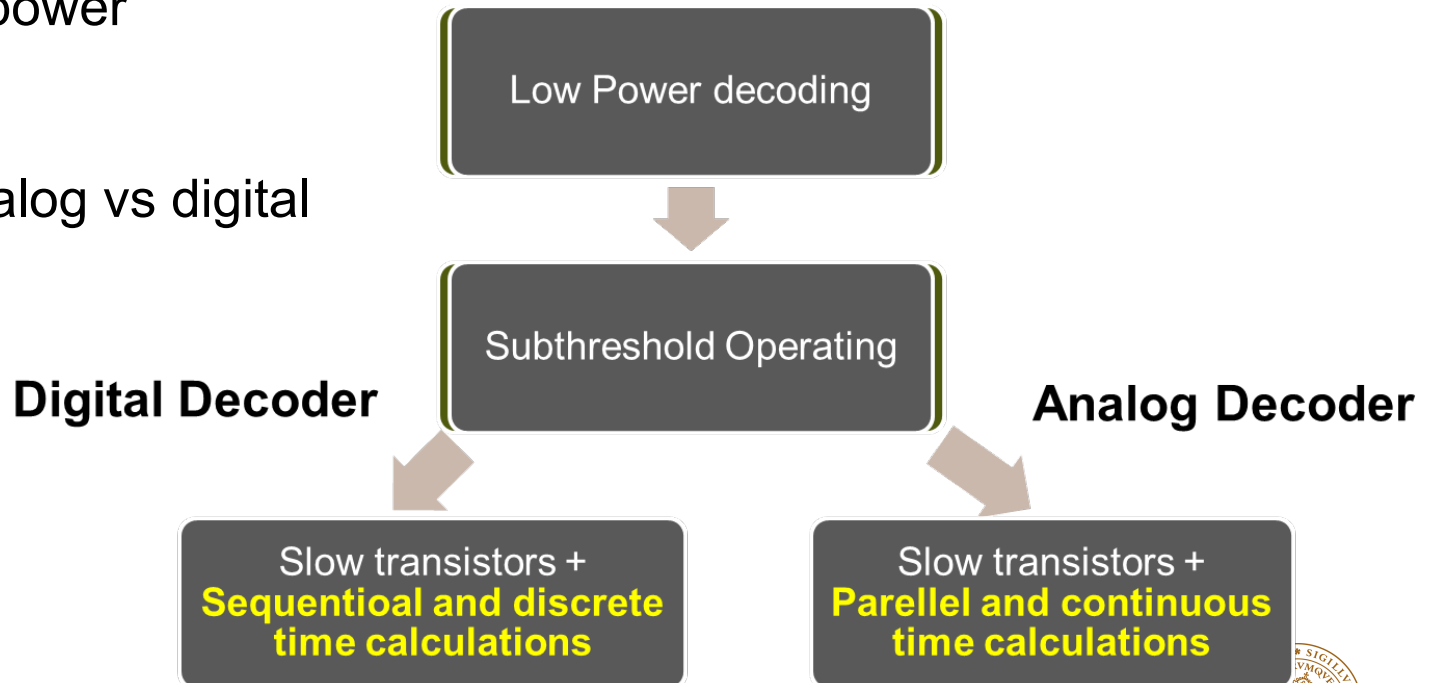
- 1mW active, 1uW standby, 1mm² in 65nm
- 125 kbit/s or above for coded transmission



Hardware Implementation Approaches

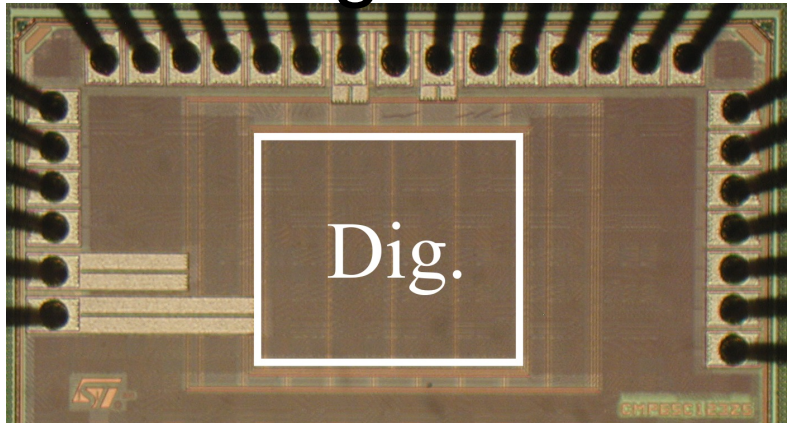
Goal:

- Below 30 μW power consumption
- Comparing analog vs digital

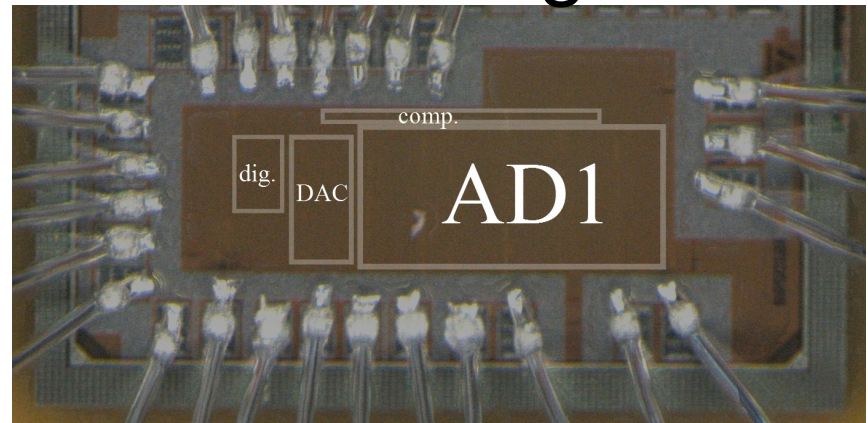


Fabricated ICs

Digital



Analog



- Analog Decoder has superior energy efficiency at higher throughputs,
42 % more efficient @ 2 Mb/s.
min $V_{DD} = 0.8$ V, 21 μ W @ 2 Mb/s Similar Area : 0.1mm²
- Digital decoder shows better energy efficiency at low V_{DD} / throughputs
33 % better @ 125 kb/s
min $V_{DD} = 0.32$ V, 2 μ W @ 125 kb/s





Single Clock High efficiency ULV DC-DC Converter with Automatic Power Controller

BABAK MOHAMMADI



High efficiency Charge-Pump

Goal

Our idea

- Charge-Pump operational in Ultra low voltages
- Low area cost, fast, high gain
- Low Power

Concept

- Improving switching quality by control logic
- Body biasing dynamically adjusted for increased efficiency
- Employing a voltage sensor to shutdown the switching activity

Conventional

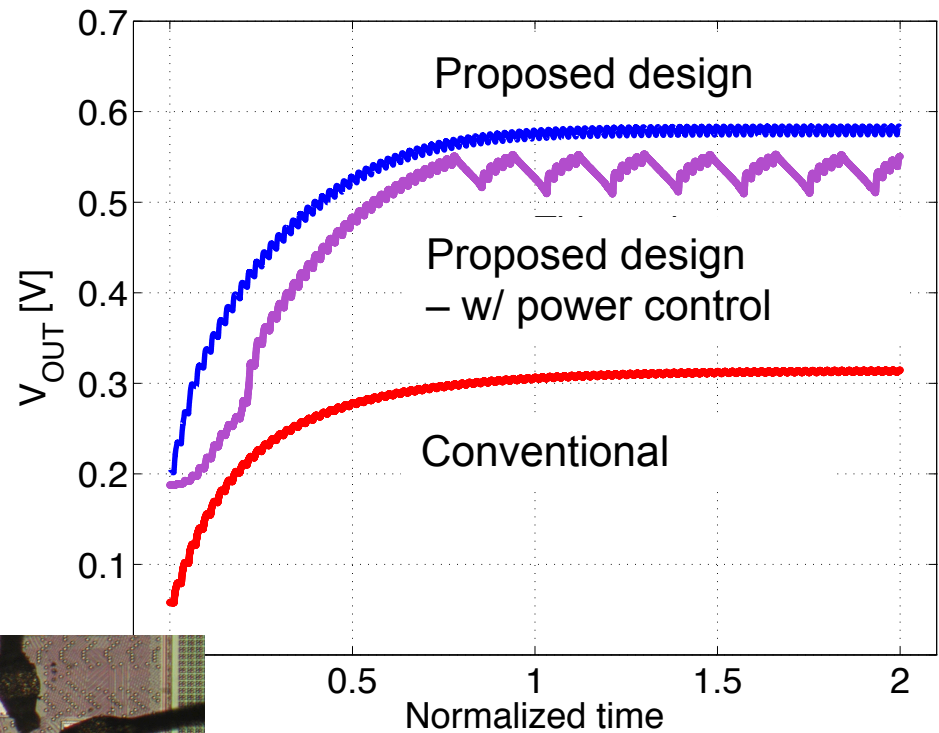


Results

W.r.t to conventional Charge-Pump with same area cost:

- More than 10x speed up
- More than 85% higher gain in ULV

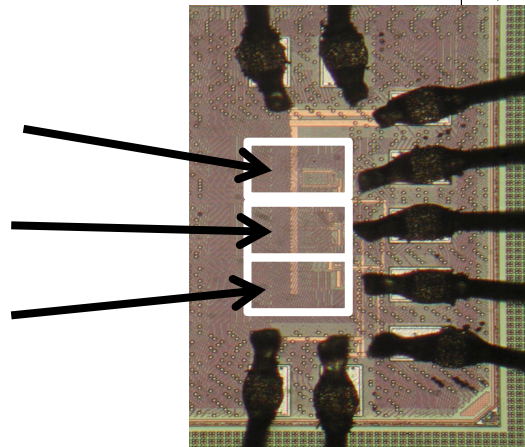
Functionality in 300mV verified by initial measurements



Conventional

Proposed design

Proposed design
- w/ power control



VDDL=250mV

Clk=500KHz

Load=2pF, 10M Ω





A $1\mu\text{W}$ wake-up receiver digital base-band with large address-space scalability

NAFISEH S. MAZLOUM



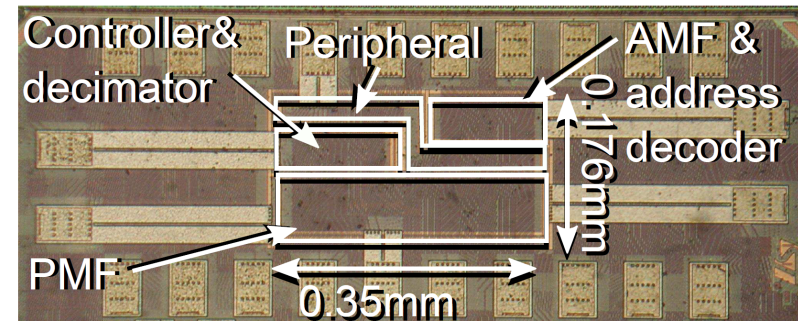
A Sub- V_t digital base-band

Goal:

An ultra-low power digital base-band for a certain wake-up beacon structure.

Measurements:

$1\mu\text{W}$ operating with 1MHz at $V_{DD} = 0.37\text{V}$



$V_{DDmin} = 0.27\text{V}$ (at 5kHz)

The properties of the architecture enable scalability for massive networks with large address-spaces.

Nafiseh will give a more detailed presentation after my talk



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Sub- V_t Variation Aware Clock Network

Yuqi Liu, Babak Mohammadi, Oskar Andersson

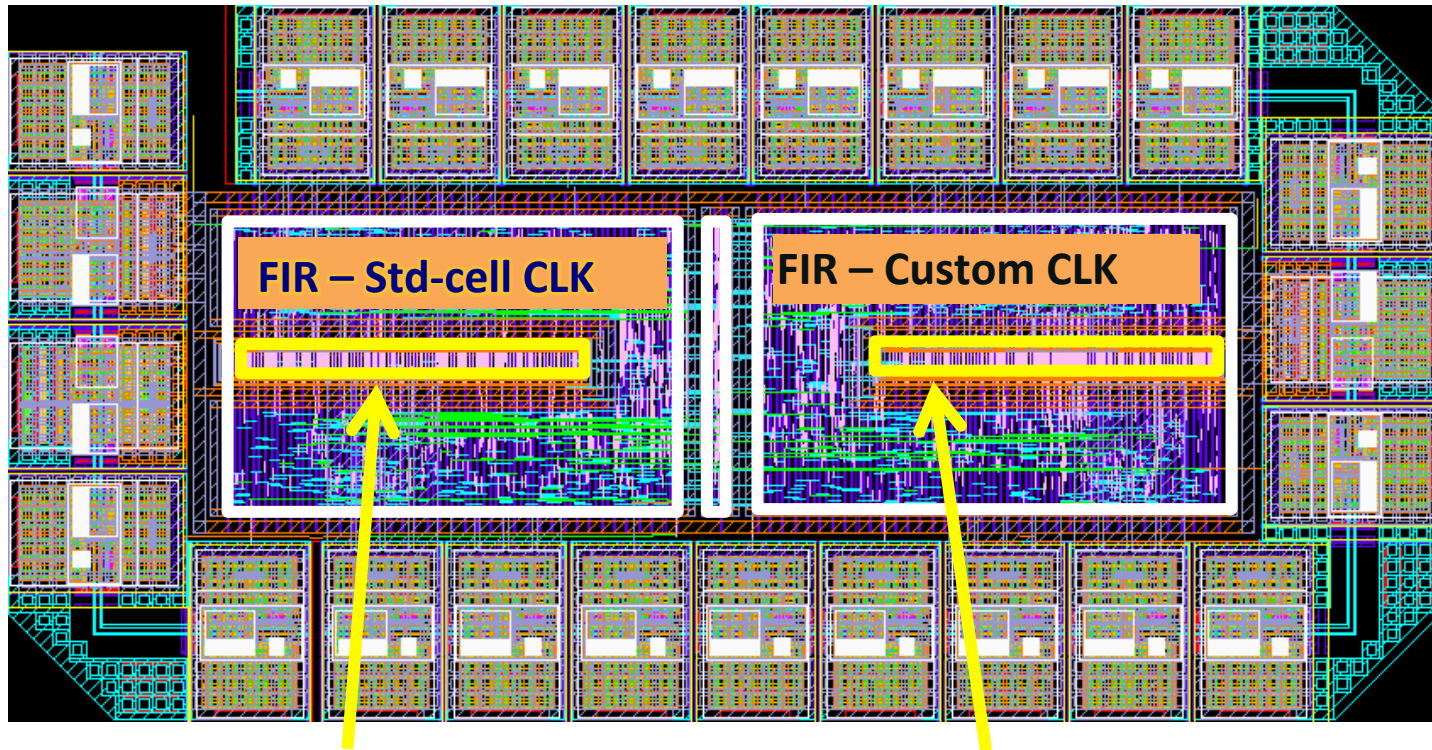
- Reduced reliability due to increased PVT variations, thus larger variations in skew and slew rate
- Quality of clock network improved by full-custom sub- V_t clock buffers

Expected Results

- 6x improvement in skew
- Lower area cost
- Less dynamic energy in clock tree



Sub- V_t Variation Aware Clock Network



Standard-cell clock buffers

Custom Clock buffers

Clock buffers in separate power domains

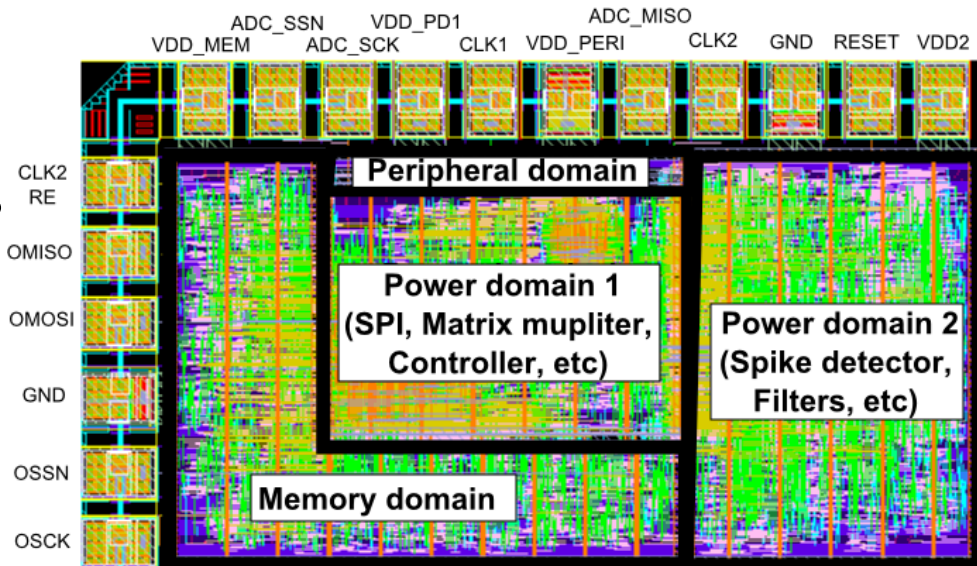
Status: Measuring queue



Low Energy Data Compression for Brain Implant

Master Thesis

- Compression ratio
Up to **125X** @ 100 spikes/s
- Architectural Optimizations
Area optimized
- Energy savings
30X from sub- V_t operation



Longyang Lin is a Phd student in Massimo Alioto group in Singapore now

Status: Measuring queue



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ÉCOLE POLYTECHNIQUE-
FÉDÉRALE DE LAUSANNE

Memories

BABAK MOHAMMADI

OSKAR ANDERSSON

PASCAL MEINERZHAGEN (EPFL, NOW AT INTEL LABS)

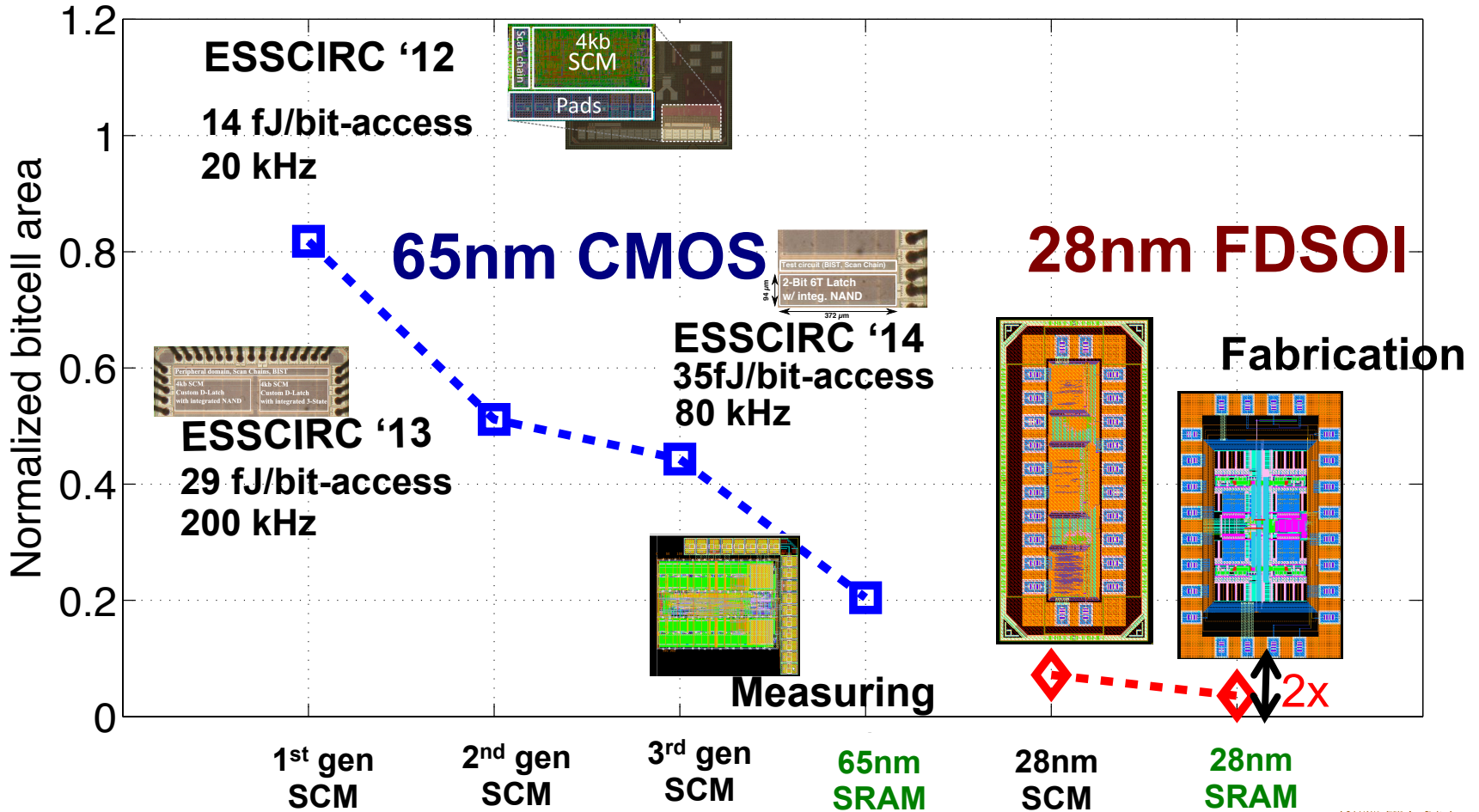
ANDREAS BURG (EPFL)

LORENZO CIAMPOLINI, ST CROLLES, FRANCE

JOSEPH NGUYEN, ST CROLLES, FRANCE



OUR ULV memories



– Area normalized to 65nm standard cell





Low Power Memory in 28 nm FDSOI






BABAK MOHAMMADI, EIT

LORENZO CIAMPOLINI AND JOSEPH NGUYEN, ST CROLLES, FRANCE



Lund/ST Collaboration Framework

- STMicroelectronics grants fabrication and supports the design on the newly developed FD28SOI technology

	Faster.	<ul style="list-style-type: none">• Advantages of FDSOI technology already demonstrated:
	Cooler.	<ul style="list-style-type: none">• +30% speed at same power → High Speed applications• -30% consumption at same speed → Low Power applications
	Simpler.	<ul style="list-style-type: none">• FDSOI process is simple & design porting from Bulk is fast• 28nm FDSOI <u>SoC</u> Level Product data available

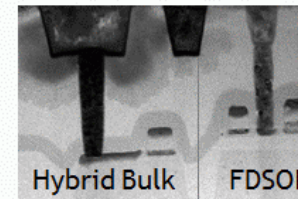
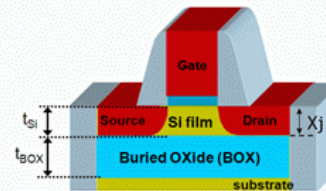
- Development done by Babak Mohammadi at Lund University



Lund/ST Collaboration Framework

- 2 months internship in STMicroelectronics Crolles (France), the fab where the FD28SOI process has been developed

- Device architecture gate-first HKMG
- *T_{Si}* 7nm, thin BOX 25nm
- BOX opened with NOSOI mask for co-integration with Bulk devices and well ties
- *Thin T_{Si}* → excellent electrostatic control
- *Undoped channel* → low variability
- *Thin BOX* → efficient and extended body biasing
→ well type used to define V_t
- 15% less process steps in 28nm FDSOI vs LP



- Possible future joint developments currently being discussed



Memory specifications and Features

- 16 kB Memory Macro operating at 20 MHz at 300 mV with a single power supply
- Custom Ultra Low-Leakage bit-cell (**PIPR**) with modified Bit-Line write
- Low-power Boost Unit based on custom charge-pump (**PIPR**) dramatically improves write & read operations
- Novel Hybrid Decoding method (**PIPR**) allows to fully exploit the Boost Unit
- New read operation mechanism (**PIPR**) allows ULV operation
- Internal scan-chain and BIST will be used to test the Macro on silicon

PIPR= Planned IPR



Custom ULL Bit-cell

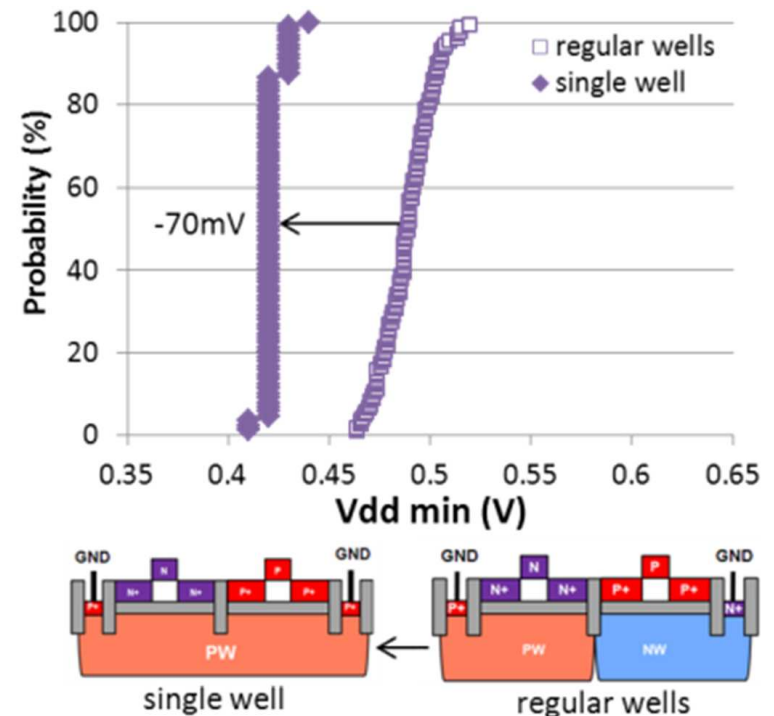
- Single-well architecture (stronger PMOS available)
- DRC-clean design using **no pushed DRC** rules;
- **Negligible area** overhead compared to industrial 8T bitcell (ST), area might improve with increased fab support.
- Bit-cell Spice characterization ongoing at ST
- Highly optimized for low leakage, lower leakage compared to existing 8T bit-cell
- Faster than existing 8T bit-cell
- Getting Closer to industrial design environment



Single P-WELL Macros

- Dynamic bias bitcell centering with single-well architecture

SRAM architecture	Features
	Regular architecture Bulk design portability Full RBB → ultra low leakage FBB VDD/2
	Flip-well architecture Full FBB → High Speed cell
	Single well architecture High SNM, Low Voltage Full RBB/FBB for bitcell recentering



Source for images: FDSOI Process/Design full solutions for Ultra Low Leakage, High Speed and Low Voltage SRAMs, R.Ranica (STMicroelectronics, Crolles, France) et al, VLSI 2013



Current Status

- Design sent for fabrication, wafers expected beg 2015

Layout view of the chip sent for fabrication Total Area $730 \times 1100 \mu\text{m}^2 = 0.803 \text{ mm}^2$





Synthesizable latched based memory in 28nm FDSOI

OSKAR ANDERSSON



SCM in 28FDSOI with Full-Custom 4-Bit Latches

Goal:

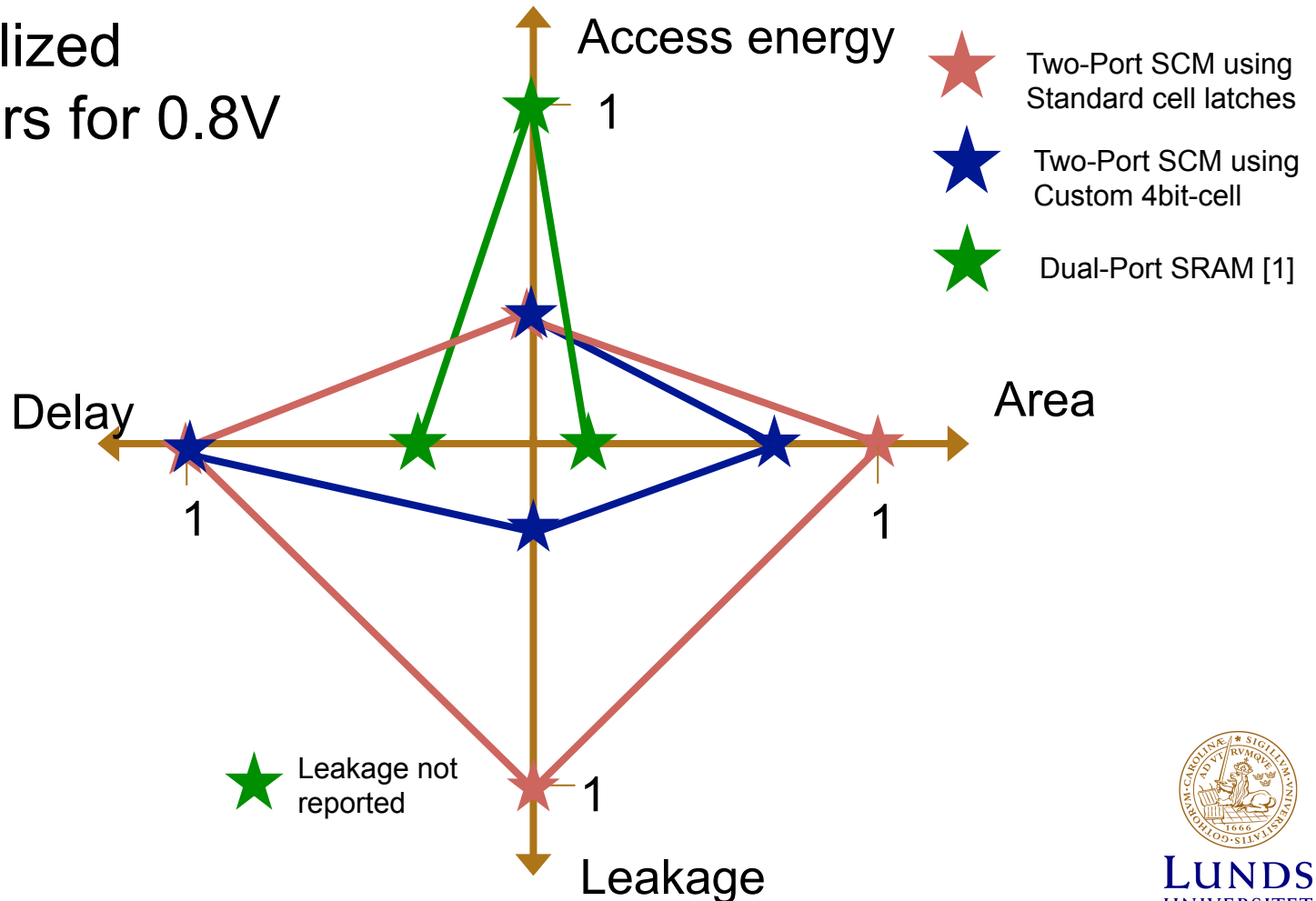
- Provide an alternative to SRAM for medium throughput system with energy awareness.
- Comparison with standard cell:
 - Decreased area
 - Reduced leakage
- Comparison with SRAM:
 - Reduced energy dissipation
 - Area penalty (?) & Delay

Status: Fabrication confirmed for October run



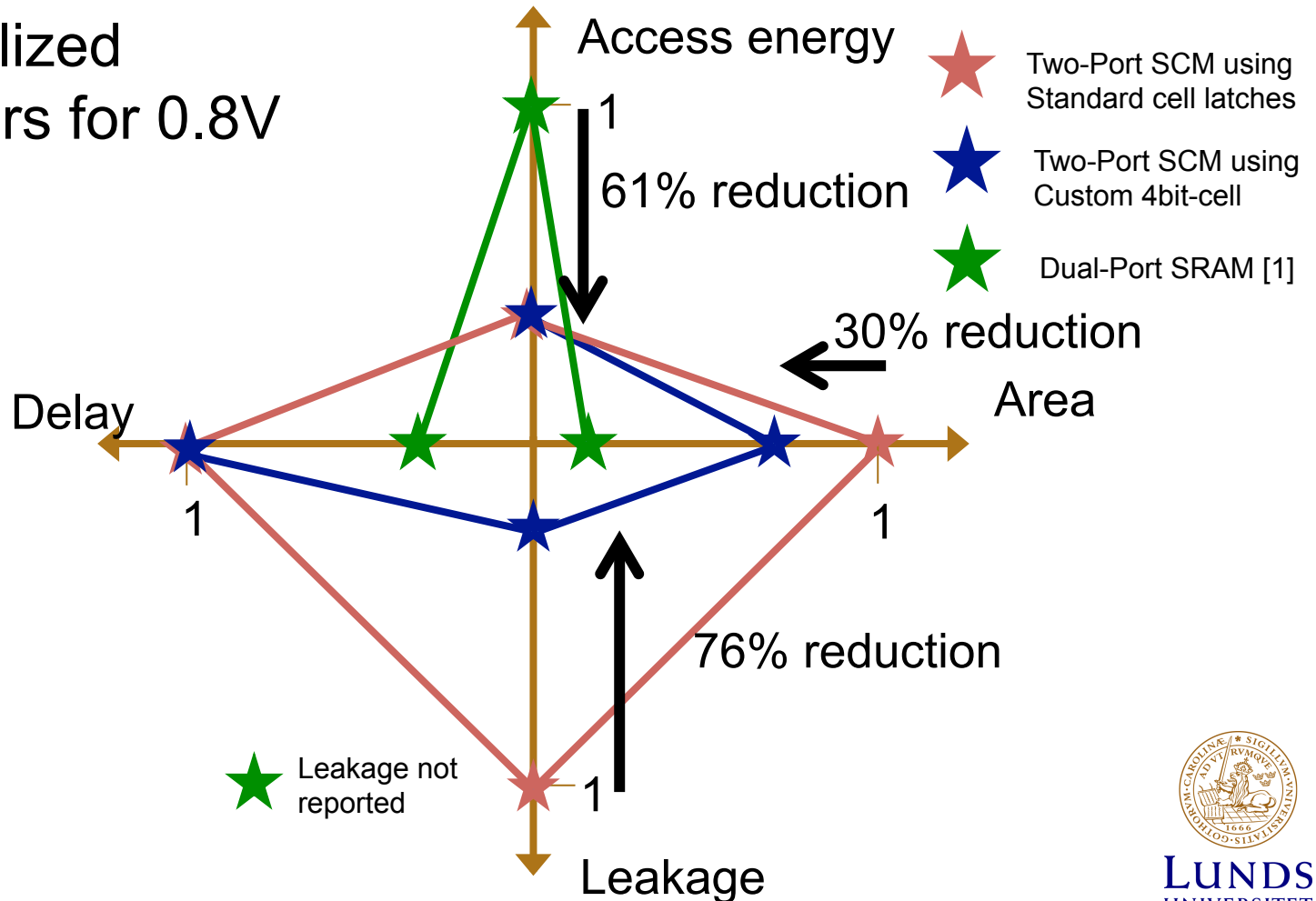
SCM in 28FDSOI with Full-Custom 4-Bit Latches

Normalized numbers for 0.8V



SCM in 28FDSOI with Full-Custom 4-Bit Latches

Normalized numbers for 0.8V



[1] Renesas: Tanaka et al., VLSI Symp., 2014





A $1\mu\text{W}$ wake-up receiver digital base-band with large address-space scalability

NAFISEH S. MAZLOUM



Questions?

